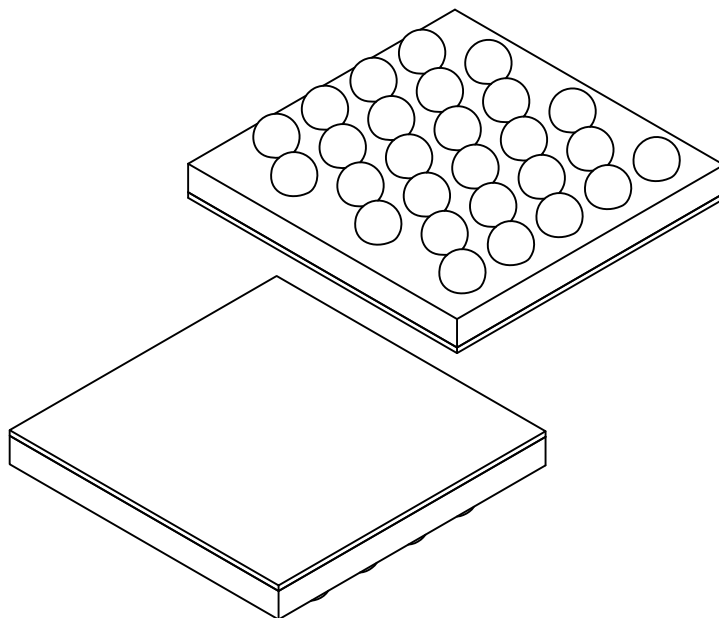


27-Ball Wafer Level Chip Scale Package (CS) - 2.199x2.215x0.483 mm Body [WLCSP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



		Units	MILLIMETERS		
Dimension Limits			MIN	NOM	MAX
Number of Terminals	N		27		
Terminal Pitch	e		0.40 BSC		
Terminal Pitch	e2		0.35 BSC		
Terminal Pitch	e3		0.20 BSC		
Terminal Offset	e4		0.191 BSC		
Terminal Offset	e5		0.177 BSC		
Overall Terminal itch	eD		1.60 BSC		
Overall Terminal Pitch	eE		1.73 BSC		
Overall Height	A	0.403	0.443	0.483	
Standoff	A1	0.17	–	0.23	
Terminal Thickness	A3	0.036	0.040	0.044	
Overall Length	D		2.199 BSC		
Overall Width	E		2.215 BSC		
Ball Width	b	0.24	–	0.30	

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated
3. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.